



SES22500-100 A/B

Shin-Etsu Silicones of America, Inc.
800-544-1745

Product Description

Shin-Etsu's SES22500-100 A/B is a two component, flowable liquid that cures into a tacky elastomer after mixing. The cure may be accelerated with the application of heat. This material is ideal for the passivation of PCB's and other vibration sensitive parts that need exceptional stress relief.

Product Features

- Ionic Purity 0.01/mil
- 2 part, fast room temperature cure system
- Super soft gel
- Low viscosity
- Colored for easy mixing verification

Typical Applications

- PCB
- Vibration sensitive parts

Typical Properties

Type	Potting Gel
Cure Type	Addition
Color	Clear/Purple
Density @ 23C (g/cm ³)	0.98
Cure Conditions	24 hrs @ 23C
Snap Time (min)	25
Penetration (1/10mm)	100
Volume Resistivity ($\Omega \cdot \text{cm}$)	2.0×10^{15}
Dielectric Constant	2.7 max @ 50Hz
Dielectric Dissipation Factor	2.0×10^{-4}

Note: Values are not for specification purposes.

Warranty- The information and data contained herein are believed to be accurate and reliable; however it is the user's responsibility to determine suitability of use. Since Shin-Etsu Silicones, Inc. cannot know all of the uses to which its products may be put or the conditions of use, it makes no warranties concerning the fitness or suitability of its products for a particular use or purpose. You should thoroughly test any proposed use of our products and independently conclude satisfactory performance in your application. Likewise, if the manner in which our products are used requires governmental approval or clearance, you must obtain it. Shin-Etsu Silicones, Inc. warrants only that its products will meet its specifications. There is no warranty of merchantability of fitness of use, nor any other expressed or implied warranties. The user's exclusive remedy and Shin-Etsu Silicones, Inc.'s sole liability is limited to refund of the price or replacement of any product shown to be otherwise than as warranted. Shin-Etsu Silicones, Inc. will not be liable for incidental or consequential damages of any kind. Suggestions of uses should not be taken as inducements to infringe any patents.